L Number	Hits	Search Text	DB	Time stamp
1	1571	@py>=2001 and (underfill$3 stress) same (chip$1 die dice$1) same (tack$2 adhe$5 glue$1 resin$4) same (bump$1 pad$1 electrode$1 lead$1)	USPAT; US-PGPUB; EPO; JPO	2004/01/09 11:11
2	239	(@py>=2001 and (underfill$3 stress) same (chip$1 die dice$1) same (tack$2 adhe$5 glue$1 resin$4) same (bump$1 pad$1 electrode$1 lead$1)) and packag$3 and underfill$3 same (chip$1 die dice$1) same (tack$2 adhe$5 glue$1 resin$4) near10 (bump$1 pad$1 electrode$1 lead$1)	USPAT; US-PGPUB; EPO; JPO	2004/01/09 11:13
3	137	((@py>=2001 and (underfill$3 stress) same (chip$1 die dice$1) same (tack$2 adhe$5 glue$1 resin$4) same (bump$1 pad$1 electrode$1 lead$1)) and packag$3 and underfill$3 same (chip$1 die dice$1) same (tack$2 adhe$5 glue$1 resin$4) near10 (bump$1 pad$1 electrode$1 lead$1)) and underfill$3 same (tack$2 adhe$5 glue$1 resin$4) near10 (bump$1 pad$1 electrode$1 lead$1) same (cur$3 bak$3 heat$3 thermal$2)	USPAT; US-PGPUB; EPO; JPO	2004/01/09 11:15